

HS12380 — HS123100

Figure 1
Typical Forward Characteristics

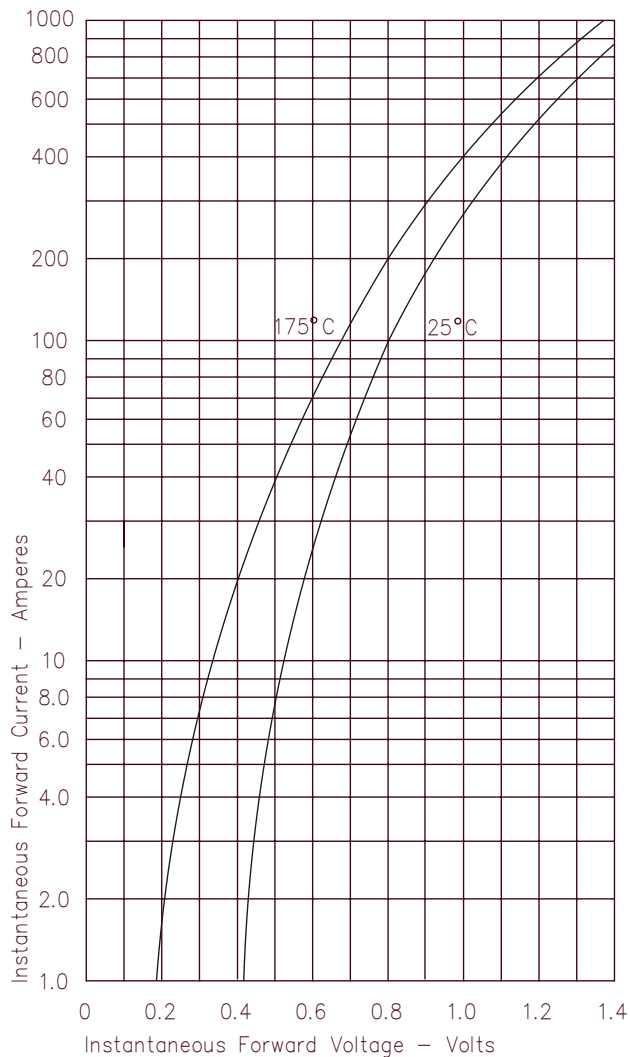


Figure 3
Typical Junction Capacitance

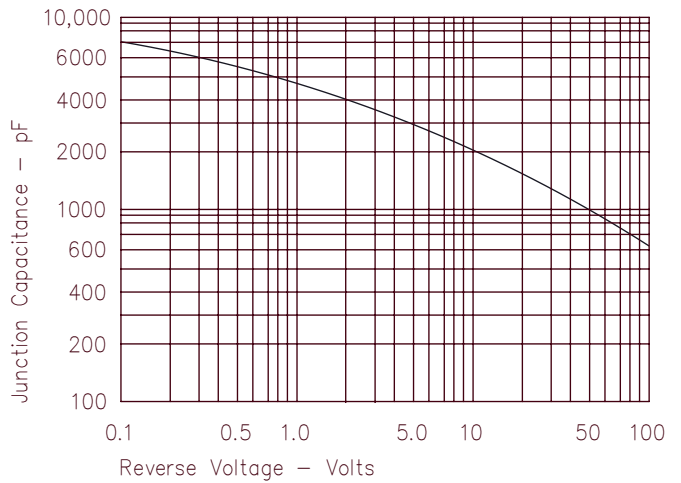


Figure 4
Forward Current Derating

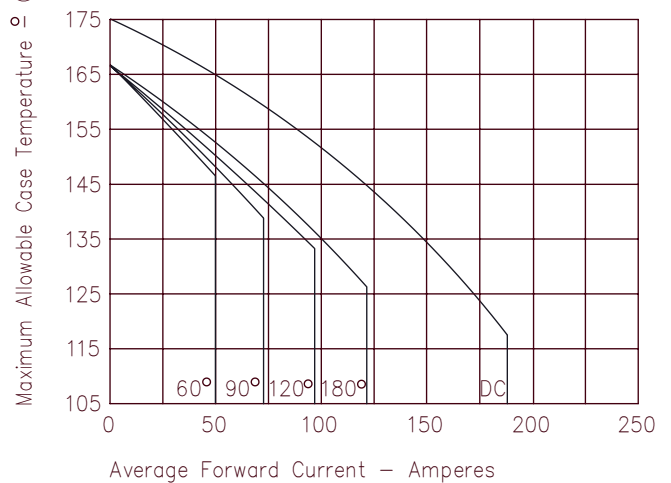


Figure 2
Typical Reverse Characteristics

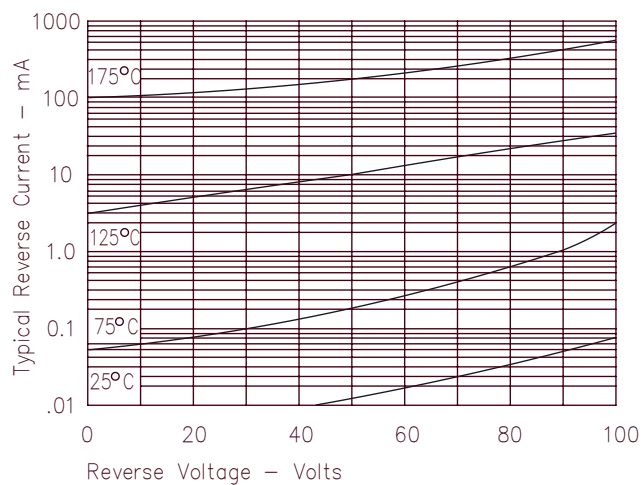
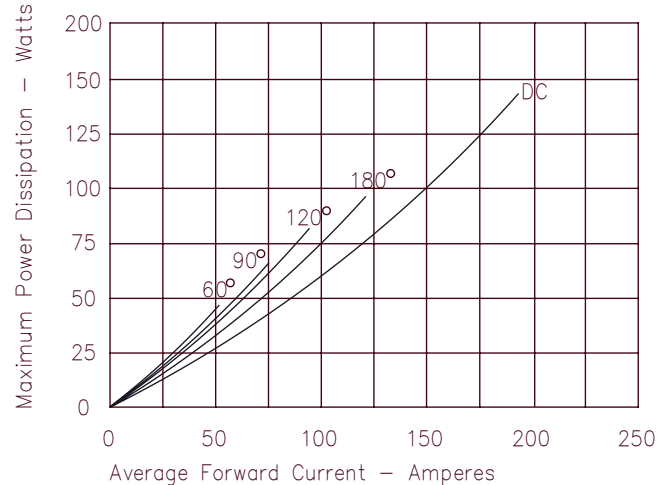


Figure 5
Maximum Forward Power Dissipation



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